RKP404KS

Composite Pin Diode for Antenna Switching

REJ03G1348-0200
Rev.2.00
Jul 03, 2006

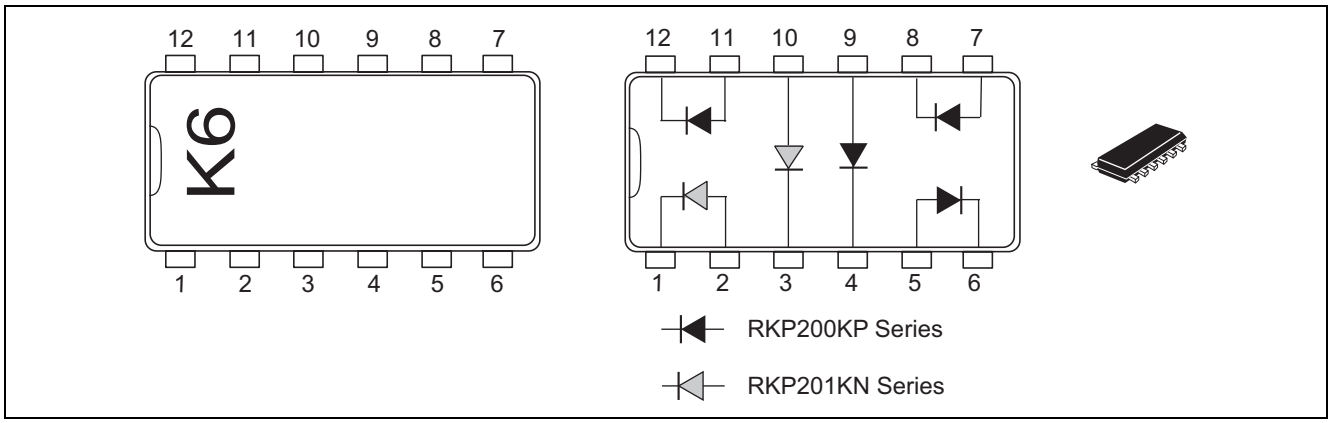
Features

- An optimal solution for antenna switching in mobile phones.
- Low capacitance. (C = 0.35 pF max)
- Low forward resistance. (rf = 2.0 Ω max @I_F = 2 mA, f = 100 MHz)
- Thin outline of diode array with six different kind elements (MFP12) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code
RKP404KS	K6	MFP12	PUSF0012ZA-A

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V_R	30	V
Forward current	I_F	100	mA
Power dissipation	Pd *	100	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	–55 to +125	°C

Note: Per one device

Electrical Characteristics (RKP200KP Series)

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse current	I_R	—	—	100	nA	V_R = 30 V
Forward voltage	V_F	—	—	1.0	V	I_F = 10 mA
Capacitance	C	—	—	0.35	pF	V_R = 1 V, f = 1 MHz
Forward resistance	r_f	—	—	1.3	Ω	I_F = 10 mA, f = 100 MHz
ESD-Capability *[1]	—	100	—	—	V	C = 200 pF, R = 0 Ω, Both forward and reverse direction 1 pulse.

Electrical Characteristics (RKP201KN Series)

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse current	I_R	—	—	100	nA	V_R = 30 V
Forward voltage	V_F	—	—	0.9	V	I_F = 2 mA
Capacitance	C	—	—	0.35	pF	V_R = 1 V, f = 1 MHz
Forward resistance	r_f	—	—	2.0	Ω	I_F = 2 mA, f = 100 MHz
ESD-Capability *[1]	—	100	—	—	V	C = 200 pF, R = 0 Ω, Both forward and reverse direction 1 pulse.

Notes: 1. Failure criterion ; I_R > 100 nA at V_R = 30 V

2. For MFP12 package, the material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Main Characteristic (RKP200KP Series)

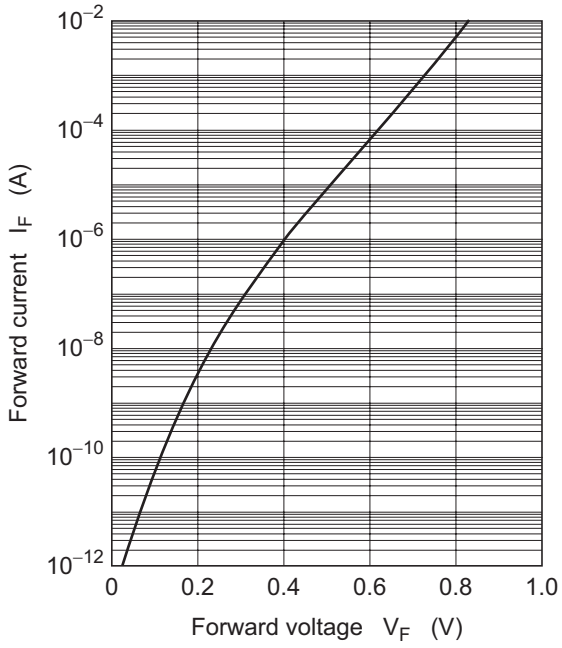


Fig.1 Forward current vs. Forward voltage

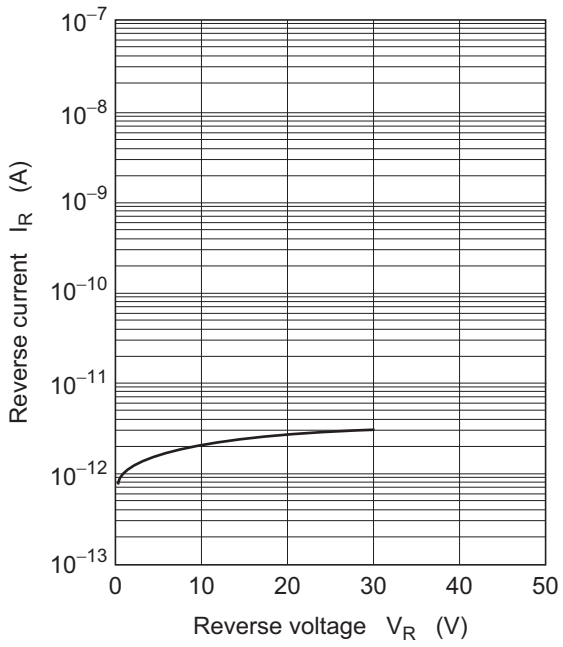


Fig.2 Reverse current vs. Reverse voltage

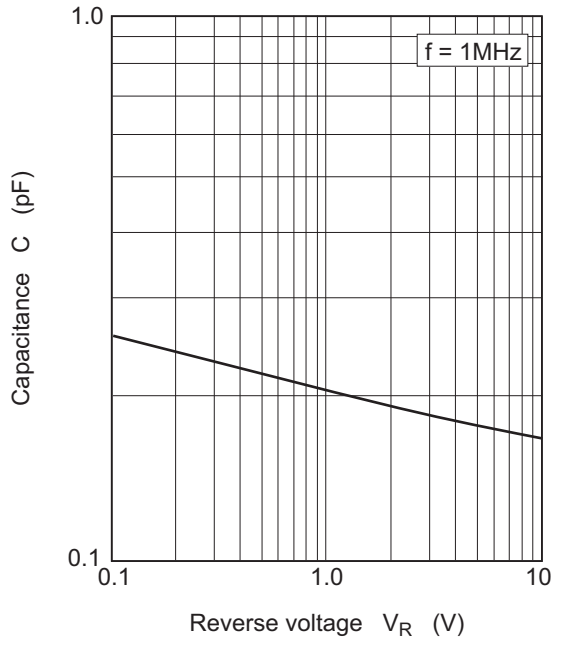


Fig.3 Capacitance vs. Reverse voltage

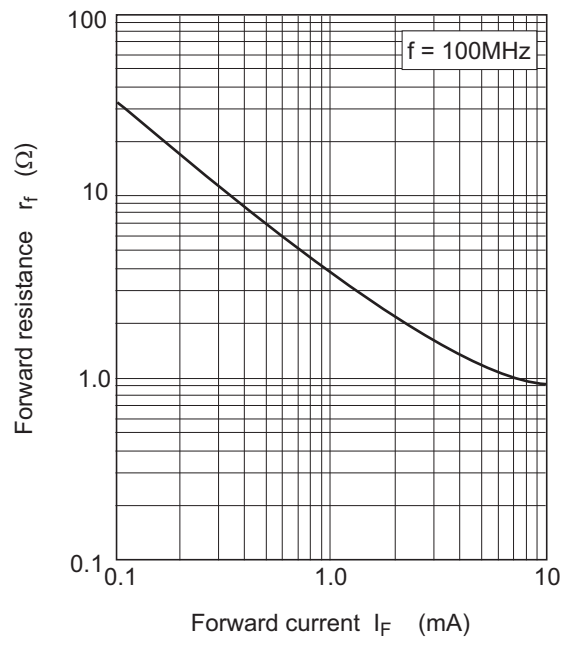


Fig.4 Forward resistance vs. Forward current

Main Characteristic (RKP201KN Series)

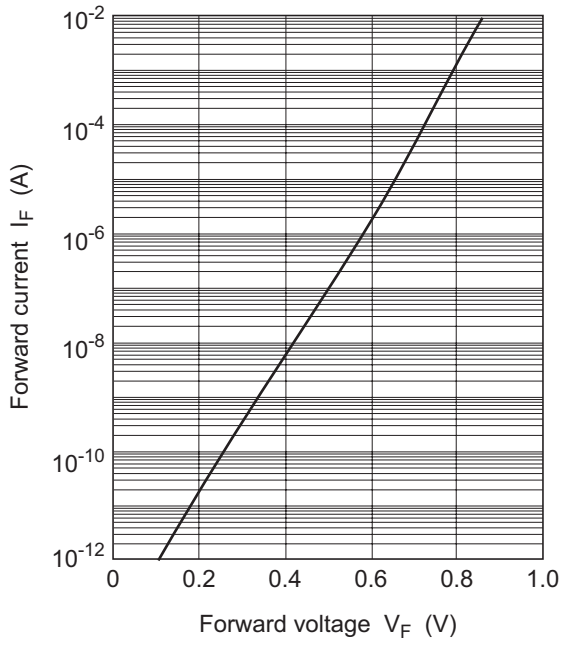


Fig.1 Forward current vs. Forward voltage

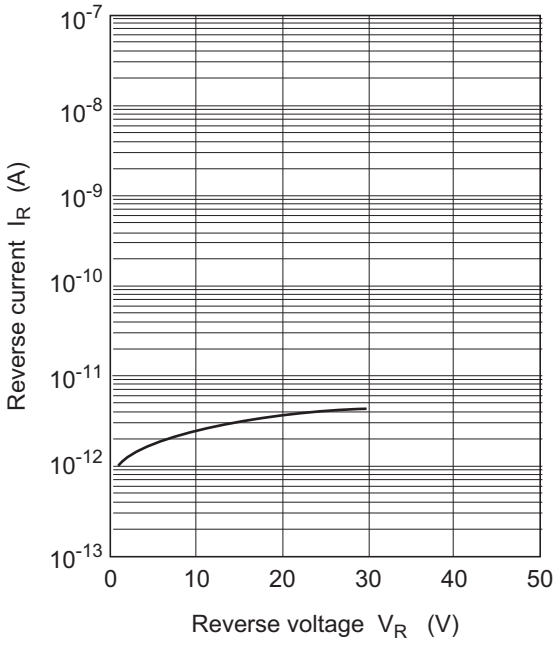


Fig.2 Reverse current vs. Reverse voltage

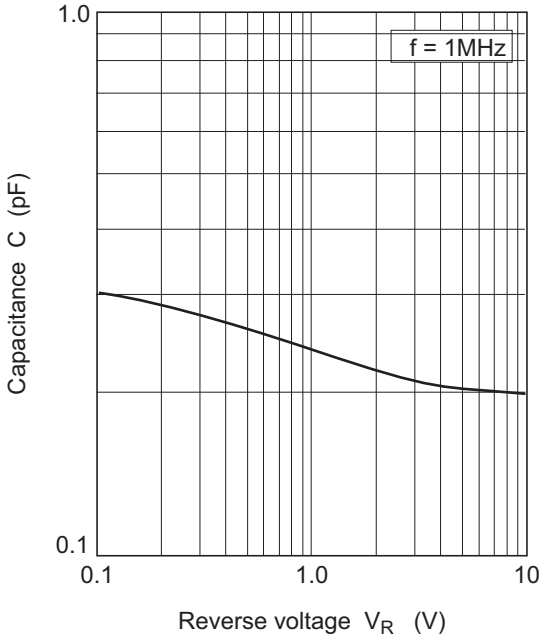


Fig.3 Capacitance vs. Reverse voltage

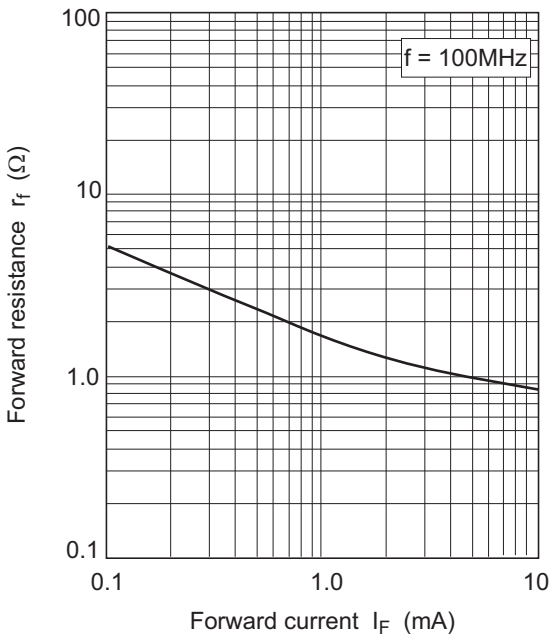
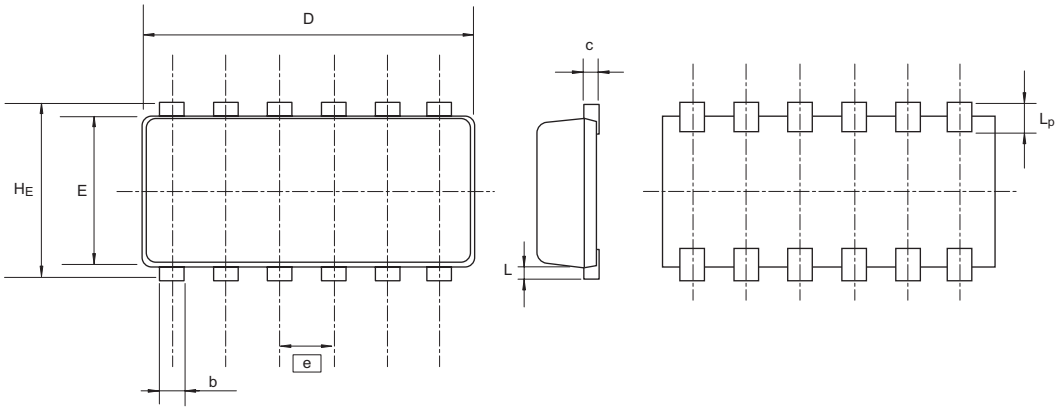
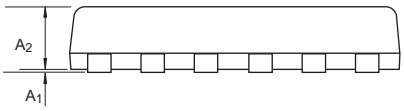


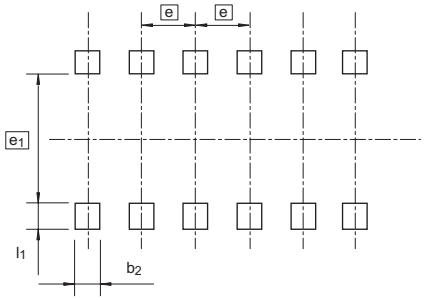
Fig.4 Forward resistance vs. Forward current

Package Dimensions

Package Name	JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
MFP12	—	PUSF0012ZA-A	MFP12V	0.004g







Pattern of terminal position areas

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
A_1	0	-	0.05
A_2	0.44	0.47	0.50
b	0.13	0.18	0.23
c	0.10	0.13	0.16
D	2.60	2.70	2.80
E	1.10	1.20	1.30
e	-	0.43	-
H_E	1.30	1.40	1.50
L	0.05	0.10	0.15
L_p	0.18	0.23	0.28
b_2	-	0.28	-
e_1	-	1.1	-
l_1	-	0.25	-

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Tel: <1> (408) 382-7500, Fax: <1> (408) 382-7501

Renesas Technology Europe Limited
Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.
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Renesas Technology (Shanghai) Co., Ltd.
Unit 204, 205, AZIACenter, No.1233 Lujiazui Ring Rd, Pudong District, Shanghai, China 200120
Tel: <86> (21) 5877-1818, Fax: <86> (21) 6887-7898

Renesas Technology Hong Kong Ltd.
7th Floor, North Tower, World Finance Centre, Harbour City, 1 Canton Road, Tsimshatsui, Kowloon, Hong Kong
Tel: <852> 2265-6688, Fax: <852> 2730-6071

Renesas Technology Taiwan Co., Ltd.
10th Floor, No.99, Fushing North Road, Taipei, Taiwan
Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

Renesas Technology Singapore Pte. Ltd.
1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632
Tel: <65> 6213-0200, Fax: <65> 6278-8001

Renesas Technology Korea Co., Ltd.
Kukje Center Bldg. 18th Fl., 191, 2-ka, Hangang-ro, Yongsan-ku, Seoul 140-702, Korea
Tel: <82> (2) 796-3115, Fax: <82> (2) 796-2145

Renesas Technology Malaysia Sdn. Bhd
Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: <603> 7955-9390, Fax: <603> 7955-9510

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